

ICP ETCHER

DRIE series

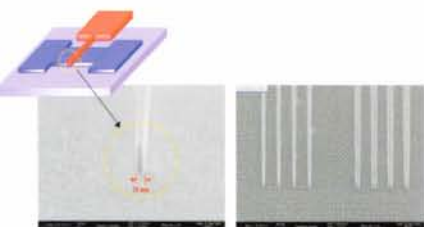
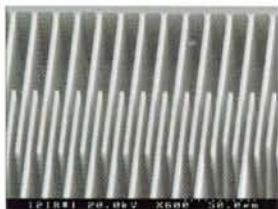


Applications

- Bulk / Poly silicon etching (MEMS & NANO)
- Dielectrics etching (SiO₂, Si₃N₄, etc.)
- Compound semiconductors etching (GaAs, GaN, etc.)
- Polyimide etching

Specifications

- Wafer size : 4inch, 6inch
- High density plasma source : ICP type
- ICP power : 2kW, 13,56MHz, Auto-matching type
- Bias power : 600W, 13,56MHz, Auto-matching type
- Loadlock chamber : stand-alone type (option : Robot type)
- Ultimate pressure
 - Process chamber : $\leq 5 \times 10^{-7}$ Torr
 - Loadlock chamber : $\leq 3 \times 10^{-3}$ Torr
- Vacuum pump
 - Process chamber : TMP + Rotary pump
 - Loadlock chamber : Rotary pump
- Process control : Auto process control
- Dimension
 - Main system : 650mm(W) × 1680mm(D) × 1600mm(H)
 - Control rack : 620mm(W) × 700mm(D) × 1740mm(H)



ICP ETCHER



Technology innovation
with advanced technology
We creat the future

Hightech Solution Corporation

ULTECH Co.,Ltd.

E vaporator

- Organic materials coating (OLED)
- Optical coating of rotational symmetry mirrors such as polygon mirrors
- Conventional materials coating
- Spintronix research (UHV & ultra low temperature system)



P lasma Immersion Ion Implanter (PIII)

- Ultra-shallow junction doping for sub-100nm CMOS
- Conformal doping of non-planar CMOS and other electronic devices
- Poly-silicon gate & trench sidewall doping
- Active matrix doping (LCD,PDP,AMOLED)



V ertical or horizontal type Furnace/LPCVD

- Low stress / Stoichiometric silicon nitride LPCVD
- Poly / Doped poly silicon LPCVD
- Silicon oxide LPCVD
- Wet / Dry oxidation
- Annealing
- LTO



S putter

- Magnetic thin films layer coating
- Opto-electronic films coating
- Industrial machinery & tools hard coating
- Conventional materials coating



D ry etcher (ICP,RIE)

- Nano etching
- Compound etching
- Polymer etching
- Bulk silicon deep etching



Major Product

R TP

- Thin Gate Oxidation(Low Pressure) (Nano device)
- Rapid Annealing(Atmospheric or Low Pressure)



S pray & Spin coater

- Uniform coating of topography such as V-grooves and trenches
- Photo resist coating
- Spin-On-Glass
- Organic materials



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